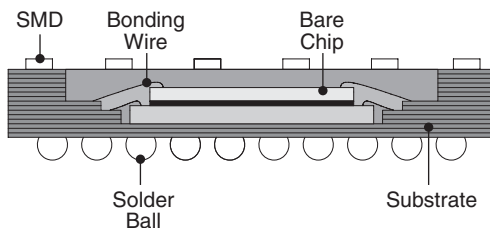


features

- Plural semiconductors in one package offers downsized system with high performance and standardization
- Wiring space saving by multilayer fine patterns on build-up substrate. No signal delay by shortened wiring distance
- Less mounting problem because of the decreasing number of the terminals

construction



Package Specifications

Item	Content
Terminal Pitch	0.8mm~
Mountable Device	<ul style="list-style-type: none"> • SMD • Bare Chip • Printed Resistor
Package	<ul style="list-style-type: none"> • SON • BGA • LGA
Substrate for Package	• LTCC

Mounting Specifications

Item	Unit	Min.	Std.	Max.	Note
Substrate Dimension	mm	—	—	100 x 100	
Substrate Thickness	mm	0.4	—	2.0	
Bare Chip Pad Pitch	μm	100	—	—	
Bare Chip Pad Dimension	μm	70	—	—	
Bare Chip Thickness	mm	0.1	0.2	—	
Molding Height	mm	0.3	1.0	1.2	Height from chip surface
Wire Length	mm	0.3	—	3.0	
Wire Loop Height	μm	100	200	—	
Wire Diameter	Au	20	25	40	
Plating	Nonelectrical Au Plating				
Substrate	• LTCC				

Molding

Material	Color
Epoxy	Black

